

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPB100N08S2-07	**Issued**	08. April 2022
MA#	MA000275855		
Package	PG-TO263-3-2	**Weight***	1566.48 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.294	0.78	0.78	7848	7848
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		194	
	non noble metal	copper	7440-50-8	304.026	19.41	19.44	194083	194335
wire	non noble metal	aluminium	7429-90-5	10.061	0.64	0.64	6423	6423
encapsulation	inorganic material	zincoxide	1314-13-2	6.737	0.43		4301	
	miscellaneous	miscellaneous	-	26.947	1.72		17202	
	plastics	epoxy resin	-	101.049	6.45		64508	
	inorganic material	silicondioxide	60676-86-0	538.930	34.40	43.00	344040	430051
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6165	6165
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.155	0.01		99	
	noble metal	silver	7440-22-4	0.194	0.01		124	
	non noble metal	lead	7439-92-1	7.423	0.47	0.49	4739	4962
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		350	
	non noble metal	copper	7440-50-8	547.666	34.97	35.02	349614	350069
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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